

Chip Scale Review

2018 Editorial Calendar

(Editorial close date: 11/20/2017)

January • February

* indicates show distribution

Enabling advanced applications in semiconductor packaging	<ul style="list-style-type: none"> • SEMI European 3D Summit Dresden, Germany (Jan 22-24) • SEMICON Korea Seoul, Korea (Jan 31-Feb 2) • SMTA Pan Pac Microelectronics Symposium Waimea, Hawaii (Feb 5-8) • 2018 FLEX Monterey, CA (Feb 12-15) • APEX Expo San Diego, CA (Feb 27-Mar1) • ISS Europe Dublin, Ireland, (Mar 4-6) • BiTS Workshop* Mesa, AZ (March 4-7) • SEMICON China* Shanghai, China (March 14-16)
Challenges and solutions to driving fan-out into high volume	
Surface analysis as a blueprint for semiconductor package manufacturing	
Laser debonding for WLP	
Adhesives for advanced packages	
Automotive sensing	
3D heterogeneous integration	
3D bump inspection	
Improving efficiency in IC testing	
Reliability and thermal management	

Ad Space Close Jan 5 - Ad Materials Close Jan 12

(Editorial close date: 1/6)

March • April

* indicates show distribution

Fan-out for RDL first process	<ul style="list-style-type: none"> • Meptec: Flexible Hybrid Electronics* San Jose, CA (April 26) • ASMC Saratoga Springs, NY (April 30-May 3) • SEMICON SE Asia Kuala Lumpur, Malaysia (May 8-10) • Meptec: Medical Electronics Symposium Dallas, TX (May 16-17) • ECTC * San Diego, CA (May 30- June 2)
Fan-out wafer and panel technology for LEDs	
Package connectivity for HDAP	
Failure analysis for 3D technologies	
Flexible hybrid electronics: System as package	
Material supply challenges for future devices	
Transfer of WLP to PLP	
Higher performance test solutions	

Ad Space Close Mar 2 - Materials Close Mar 9

(Editorial close date: 3/9)

May • June

* indicates show distribution

Market forecast	<ul style="list-style-type: none"> • IEEE/SW Test Workshop (SWTW) San Diego, CA (June 3-6) • Sensors Expo San Jose, CA (June 26-28) • SEMICON West * San Francisco, CA (July 10-12)
Smart innovations in automotive electronics	
Die attach	
Biodegradable and recyclable materials	
Sequential 3D integration	
One micron RDL structures	
Smart burn-in & test sockets	
Challenges of flip chip MEMS devices	
Next-gen IOT solutions	

Ad Space Close May 4 - Ad Materials Close May 11

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